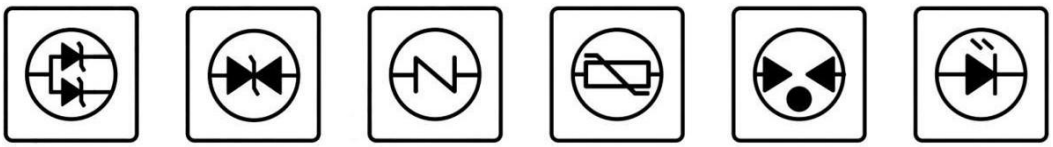
MSKSEMI 美森科
SEMICONDUCTOR



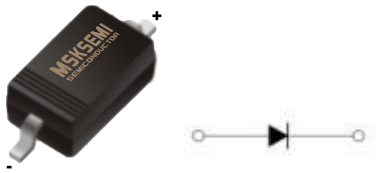
BAS16WX

Product specification

FEATURES

- Fast Switching Speed
- For General Purpose Switching Applications
- High Conductance

Reference News

PACKAGE OUTLINE	MARKING
 SOD-323	A6

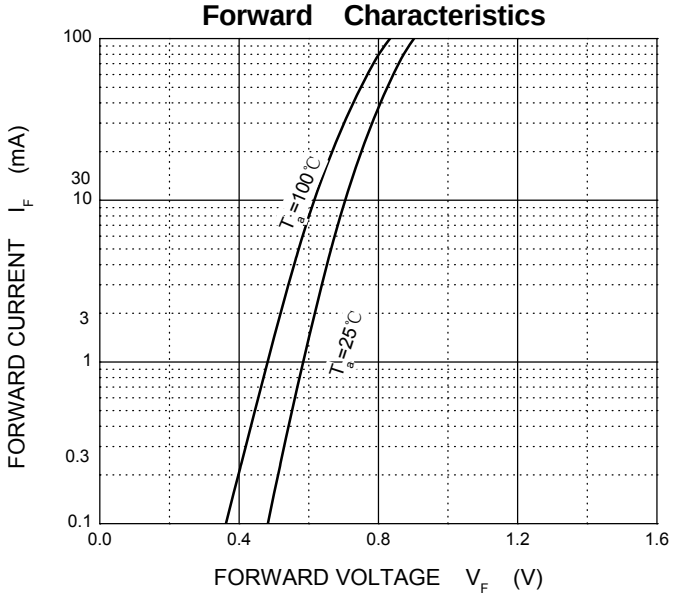
Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25℃

Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	V_{RM}	85	V
Peak Repetitive Peak Reverse Voltage **Working Peak Reverse Voltage** **DC Blocking Voltage**	V_{RRM} V_{RWM} V_R	75	V
RMS Reverse Voltage	$V_{R(RMS)}$	53	V
Average Rectified Output Current	I_O	100	mA
Non-Repetitive Peak Forward Surge Current @t=8.3ms	I_{FSM}	2.0	A
Power Dissipation	Pd	200	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	625	℃/W
Operation Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	℃

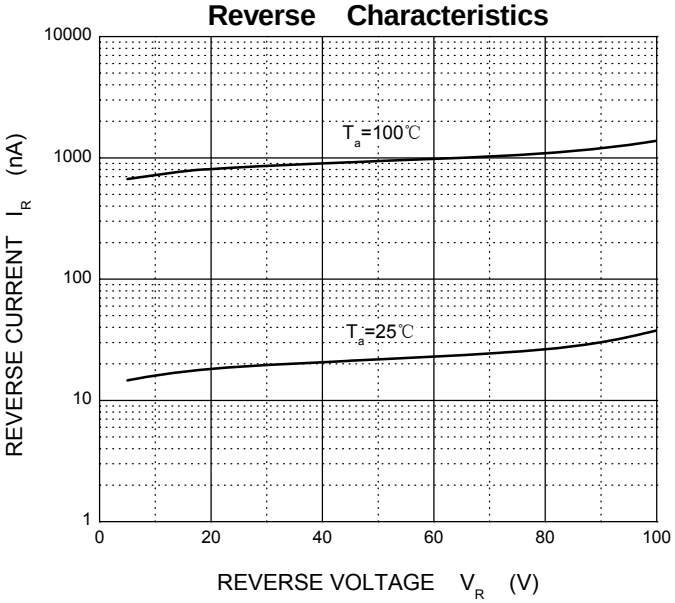
Electrical Ratings @Ta=25℃

Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Reverse voltage	$V_{(BR)}$	I_R=10μA	75			V
Forward voltage	V_F	I_F=1mA			0.715	V
		I_F=10mA			0.855	
		I_F=50mA			1	
		I_F=150mA			1.25	
Reverse current	I_R	V_R=75V			1	μA
Total capacitance	C_{tot}	V_R=0V,f=1MHz			2	pF
Reverse recovery time	t_{rr}	I_F= I_R=10mA, I_{rr}=0.1×I_R, R_L=100Ω			6	ns

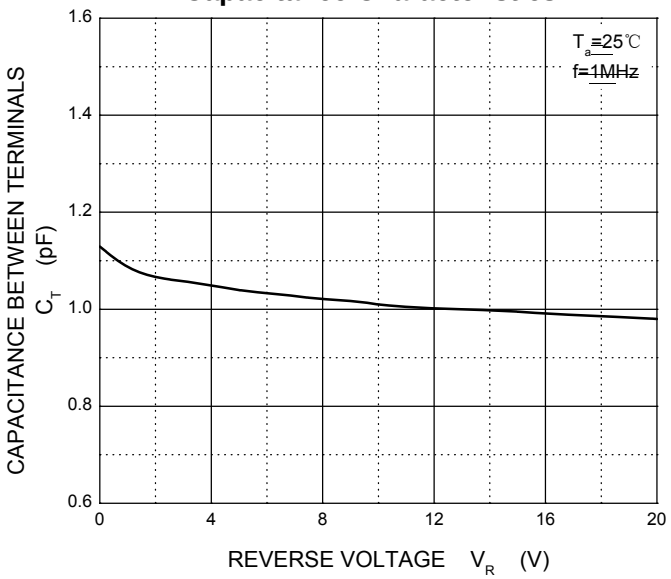
Forward Characteristics



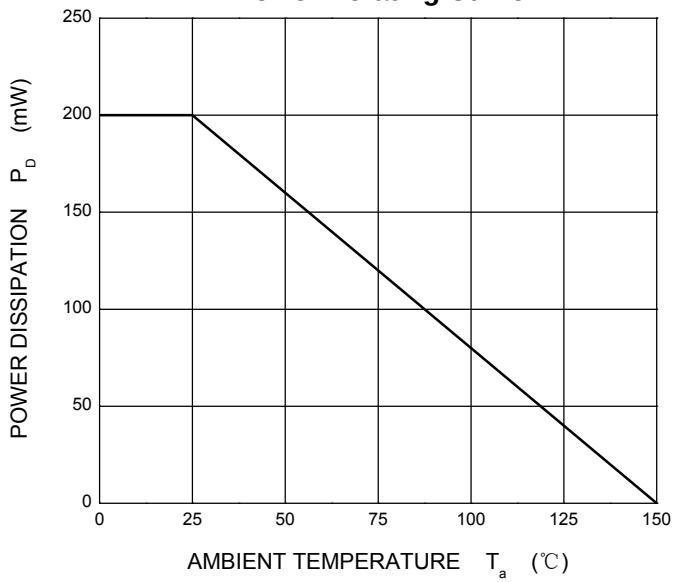
Reverse Characteristics



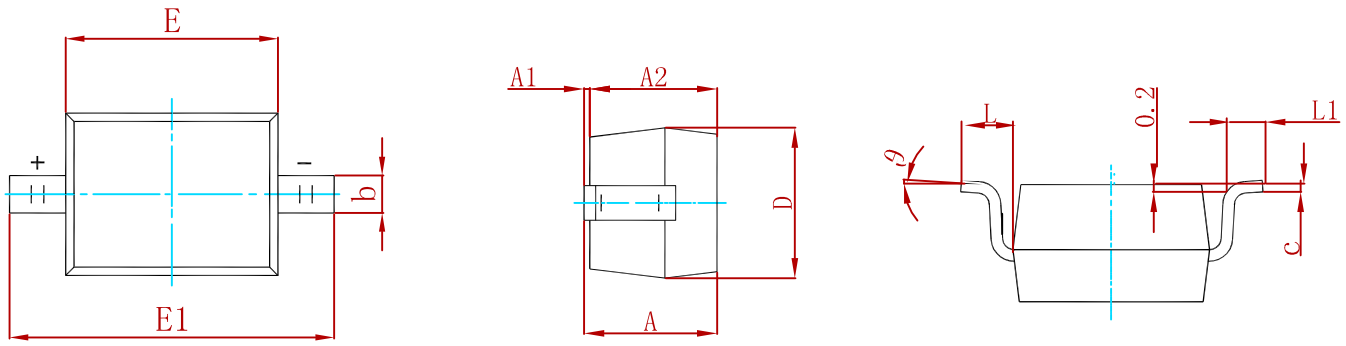
Capacitance Characteristics



Power Derating Curve

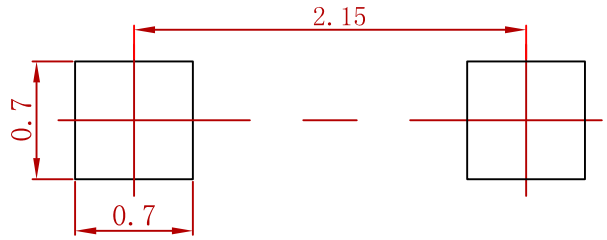


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF.		0.019 REF.	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAS16WX	SOD-323	3000

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